

Excellent Integrated System Limited

Stocking Distributor

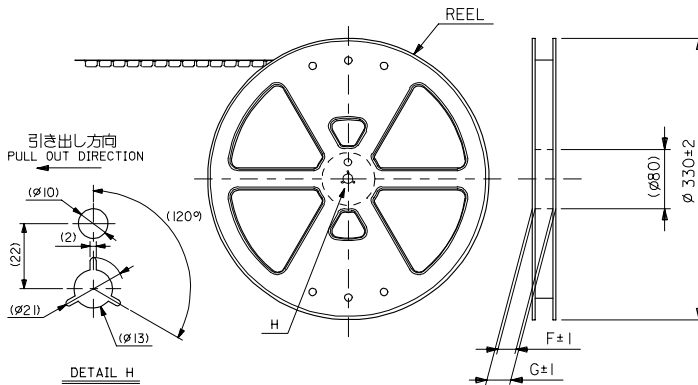
Click to view price, real time Inventory, Delivery & Lifecycle Information:

[Molex Connector Corporation](#)
[0556504078](#)

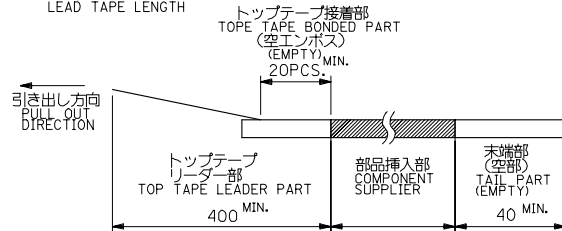
For any questions, you can email us directly:

sales@integrated-circuit.com

10 9 8 7 6 5 4 3 2 1

注)
NOTES

- 製品番号 55650-***81 詳細寸法については、製品単体図面を参照下さい。
IN THE PACKAGE PART NUMBER 55650-***81 DETAILED DIMENSIONS,
SEE SALES DRAWING FOR CONNECTOR.
- 梱包数量: 2000個/リール
NUMBER OF CONNECTORS: 2000 PCS/REEL.
- リードテープ長さ
LEAD TAPE LENGTH



- トップテープの剥離強度: (剥離方向は下図参照)
PEELING OFF FORCE OF TOP TAPE (PELLING DIRECTION AS SHOWN IN FOLLOWING FIGURE.)
0.1~1.3N {10~130gf}

尚、本規格値は、出荷時に適用。
THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT.
(但し、輸送時に剥離が発生しない事。)
(PEEL OFF SHOULD NOT BE ALLOWED, DURING TRANSPORTATION.)

- 材料
MATERIAL
キャリアテープ: ポリプロピレン (PP)
CARRIER TAPE: POLYPROPYLENE (PP)
トップテープ: PET, PE, PEF
TOP TAPE: PET, PE, PEF
リール: ポリスチレン
REEL: POLYSTYRENE

- 本製品は 55650-***8 の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 55650-***8.

55650-***78		MODEL NO.	
DESIGN UNITS	METRIC	THIRD ANGLE PROJECTION	
DRAWN BY DATE		TITLE	
M.NINOMIYA 2004/02/17		EMBOSSD TAPE PACKAGE FOR 55650-***81 -LEAD FREE-	
CHECKED BY DATE		K.TOJO 2004/02/17	
APPROVED BY DATE		M.SASAO 2004/02/17	
MATERIAL NO.		DOCUMENT NO.	
SEE SHEET 2		SD-55650-012	
SIZE		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	
A3		1 OF 2	

10 9 8 7 6 5 4 3 2 1

F

E

D

C

B

A

F

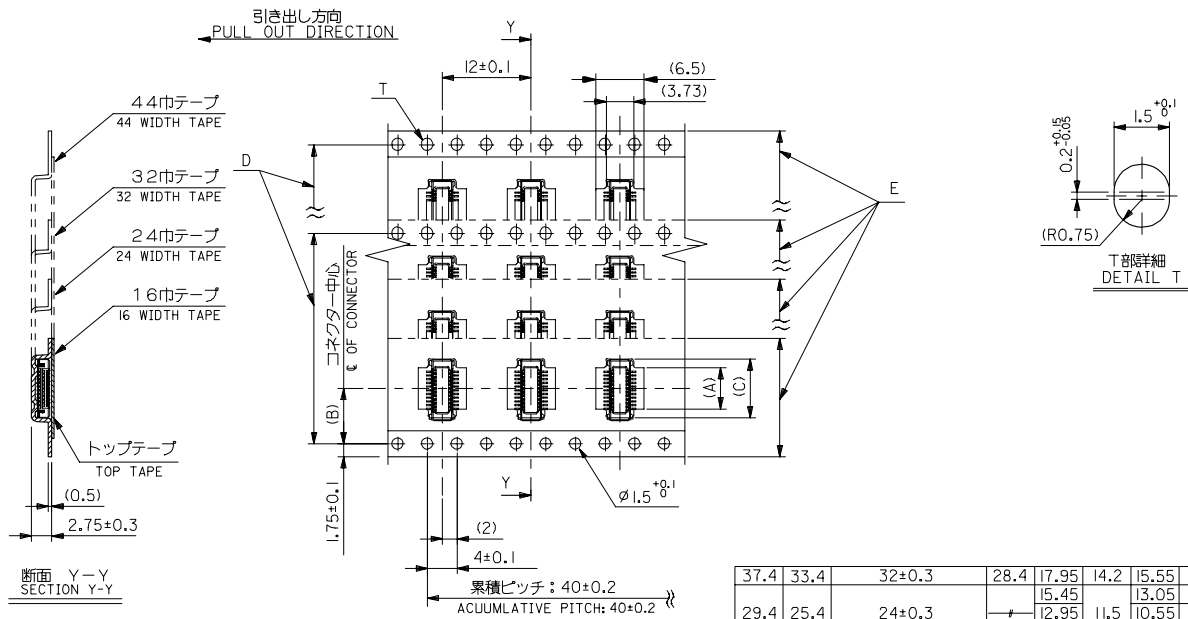
E

D

C

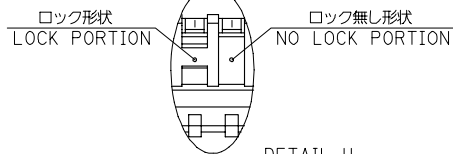
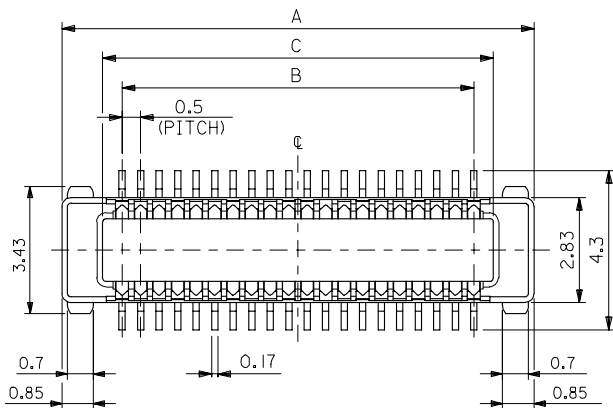
B

A



37.4	33.4	32±0.3	28.4	17.95	14.2	15.55	55650-6078	60
29.4	25.4	24±0.3		15.45	11.5	13.05	55650-5078	50
				12.95		10.55	55650-4078	40
				10.45		8.05	55650-3078	30
G	F	E	D	(C)	(B)	(A)	製品番号 MATERIAL NO.	極数 CIRCUITS

REVISED EC NO: J2007-0848 2006/10/31 DRAWN: YAOYAGI CHKD: K. TOYODA 2006/11/01 APP: NIKITA 2006/11/01	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	 THIRD ANGLE PROJECTION	
		10 UNDER	±0.2	DRAWN BY M. NINOMIYA		DATE 2004/02/17		EMBOSSED TAPE PACKAGE FOR 55650-***81 -LEAD FREE-	
		10 OVER 30 UNDER	±0.25	CHECKED BY K. TOJO		DATE 2004/02/17			
		30 OVER	±0.3	APPROVED BY M. SASAO		DATE 2004/02/17			
		ANGULAR ±3°		MATERIAL NO.		DOCUMENT NO.		MOLEX INCORPORATED SD-55650-012	
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART		SHEET NO. 2 OF 2			
A	REV	SIZE 3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

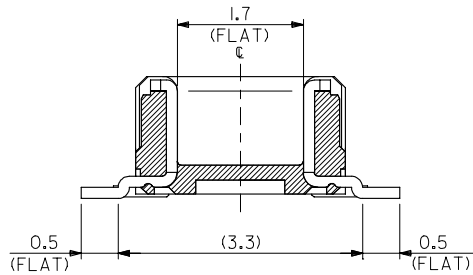
注記
NOTES:

- 材質
MATERIAL
ハウジング: LCP (液晶ポリマー)、ガラス充填、黒色、UL94V-0
HOUSING: LCP (LIQUID CRYSTAL POLYMER), GLASS FILLED, BLACK, UL94V-0
ターミナル: 銅合金 (t=0.15)
TERMINAL: COPPER ALLOY (t=0.15)
ネイル: 銅合金 (t=0.15)
NAIL: COPPER ALLOY (t=0.15)
- メッキ仕様
PLATING
ターミナル
TERMINAL
接点部: 金メッキ 0.25マイクロメートル以上
CONTACT AREA: GOLD 0.25 MICROMETER MINIMUM
半田付け部: 金メッキ 0.35マイクロメートル以下
SOLDER TAIL AREA: GOLD 0.35 MICROMETER MAXIMUM
下地メッキ: ニッケルメッキ 1.5マイクロメートル以上
UNDER PLATING: NICKEL 1.5 MICROMETER MINIMUM
ネイル
NAIL
銅メッキ 1.0マイクロメートル以上
TIN 1.0 MICROMETER MINIMUM
下地メッキ: ニッケルメッキ 1.0マイクロメートル以上
UNDER PLATING: NICKEL 1.0 MICROMETER MINIMUM
- テール平坦度は、0.08ミリメートル以下。テールとネイルを併せた平坦度は、0.1ミリメートル以下。
TAIL COPLANARITY TO BE 0.08 MAXIMUM. TAILS AND NAILS COPLANARITY TO BE 0.1 MAXIMUM.
- 嵌合相手: 54363-****
MATED CONN.: 54363-****
- 本製品は55650-****の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 55650-****

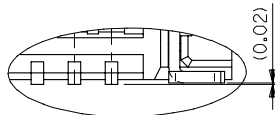
—#—	28.05	27	30.25	55650-1181	110
4	18.05	17	20.25	55650-0781	70
8	15.55	14.5	17.75	55650-0681	60
12	13.05	12	15.25	55650-0581	50
20	10.55	9.5	12.75	55650-0481	40
30	8.05	7	10.25	55650-0381	30
20	5.55	4.5	7.75	55650-0281	20

ロック数 LOCKS	C	B	A	製品番号 MATERIAL NO.	極数 CIRCUITS
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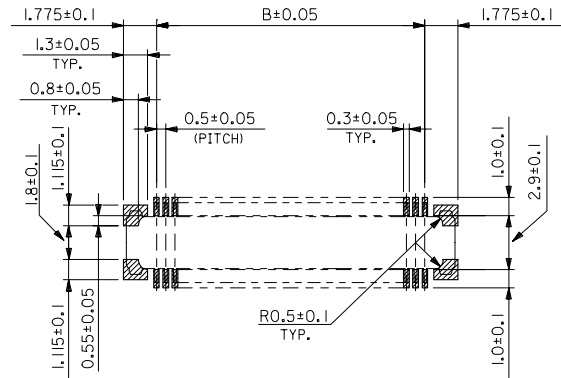
REVISED	EC NO. J2008-0540	TRIMMED NO. 55650-****	DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
	DRWN:AY061	DESCRIPTION 2007/09/03 2007/09/03 CHKD:Y001A APPR:NUK1A	GENERAL TOLERANCES (UNLESS SPECIFIED)		DRAWN BY DATE M. NAGATA 2004/03/09				TITLE 0.5 MM PITCH B/B CONN. PLUG NAIL ASS'Y (H=2MM) -LEAD FREE- MOLEX INCORPORATED
	10 UNDER		±0.2	CHECKED BY DATE K. TOJO 2004/03/09					
	10 OVER 30 UNDER		±0.25	APPROVED BY DATE M. SASAO 2004/03/09					
	30 OVER		±0.3	MATERIAL NO. SEE TABLE					
	ANGULAR ±3°		DOCUMENT NO. SD-55650-013						
REV		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SHEET NO. 1 OF 2		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			



製品断面図 (半田付け部、吸着面寸法)
DETAIL FOR SOLDERING AND VACUUM AREA



DETAIL T
T部詳細



推奨基板寸法
RECOMMENDED PCB PATTERN LAYOUT
(SCALE 5:1)

REVISED EC NO.: J2008-0540 DRAWN: YAOJG1 2007/09/03 CHKD: KTOYDA 2007/09/03 APPR: NUKITA 2007/09/04	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	 THIRD ANGLE PROJECTION	
		10 UNDER	±0.2	DRAWN BY M. NAGATA	DATE 2004/03/09	TITLE 0.5 MM PITCH B/B CONN. PLUG NAIL ASSY (H=2MM) -LEAD FREE-			
		10 OVER 30 UNDER	±0.25	CHECKED BY K. TOJO	DATE 2004/03/09				
		30 OVER	±0.3	APPROVED BY M. SASAO	DATE 2004/03/09	MOLEX INCORPORATED			
		ANGULAR	±3 °	MATERIAL NO.					
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE SHEET 1		SD-55650-013		2 OF 2	
				SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			